

## DOCUMENT CHANGE REQUEST

483 DCR number Changes required for: Qualification Originator: nicolas martini Date: 2009/03/30 Date sent: 2009/03/30 Organisation: CNES Status: IMPLEMENTED Title: Resistors fixed film chips, based on type P HR Number: 4 4001/023 Issue: Other documents affected: 4001/025-4 Page: 1) Tittle: 2) Appendix A: 3) Appendix A: Paragraph: 1) Tittle: 2) Appendix A: 3) Appendix A: Original wording: Proposed wording: 1) Tittle: Replace PHR with P or add PFR to PHR. 2) Appendix A: replace 2XXXX with 26000. 3) Appendix: In first box, Deviation from Generic specification, screening test (Chart F3): add Para. 8.3.3 High and Low Temperature Measurement (TC) TC measurements are performed at +25°C and +75°C at Front-end level on each wafer on 5 areas. -55°C/+155°C acceptance criteria are guaranted through the correlation table given in VISHAY specification CM-SF-00210.

Justification:

- 2) Editorial change
- 3) Test reduction as agreed by VISHAY TRB and CNES.

Attachments:
N/A
Modifications:
the following minor editorial amendments to the text to be included in the Detail spec on points 1 & 3 of DCR483 for clarification purposes:
For 4001/023 1 - amend title to be based on type "PHR and PFR" (similar to 4001/025)
3 - Appendix A, add new item:
Items Affected High and Low Temperatures Electrical Measurements
Description of Deviations  All tests at high and low temperatures are guaranteed but tested based on temperature coefficient measurements performed on each wafer at +25C and +75C in accordance with VISHAY specification CM-SF-00210.
For 4001/025 Only item 3 of DCR483 applies to 4001/025 (amended as follows):
3 - Appendix A, add new item:
Items Affected High and Low Temperatures Electrical Measurements
Description of Deviations  All tests at high and low temperatures are guaranteed but tested based on temperature coefficient and relative temperature coefficient measurements performed on each wafer at +25C and +75C in accordance with VISHAY specification CM-SF-00210.
Approval signature:
Homes
Date signed:
2009-03-30